

FIG. 3

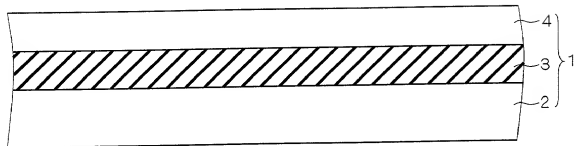


FIG. 4

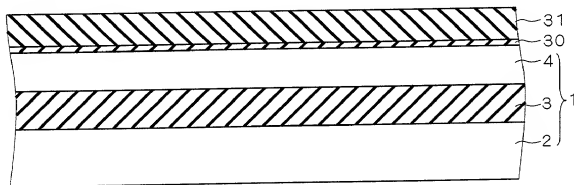


FIG. 5

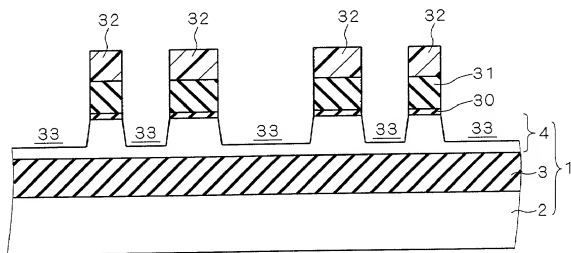


FIG. 6

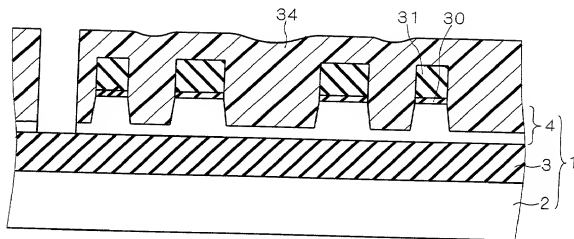


FIG. 7

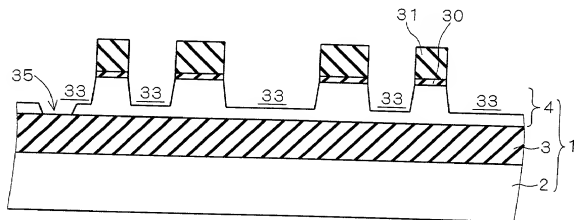


FIG. 8

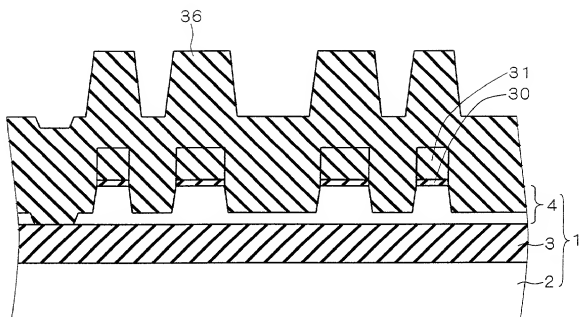


FIG. 9

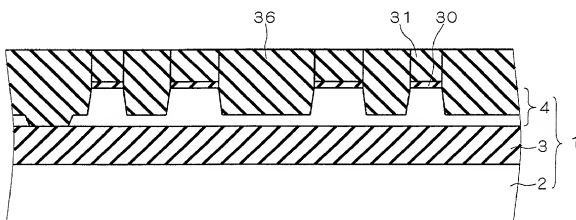


FIG. 10

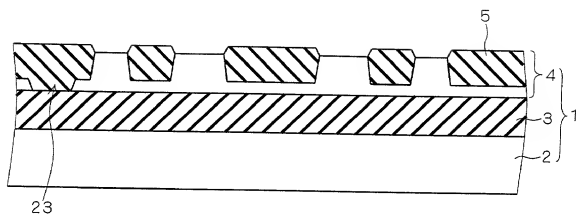


FIG. 11

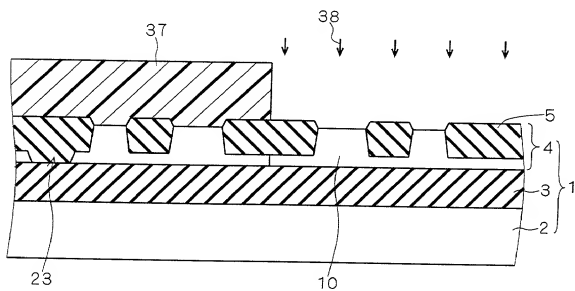


FIG. 12

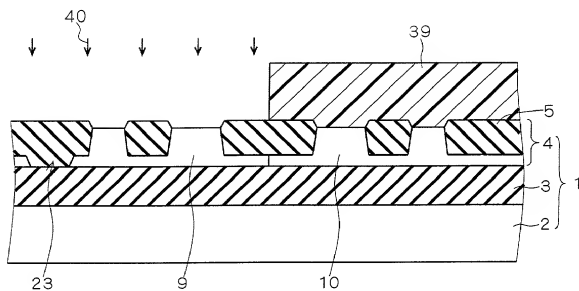
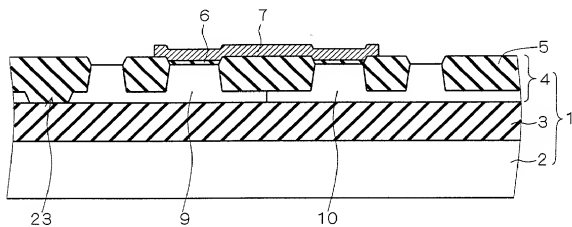


FIG. 13



F / G. 14

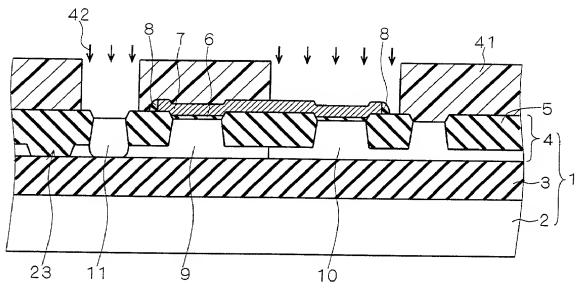


FIG. 15

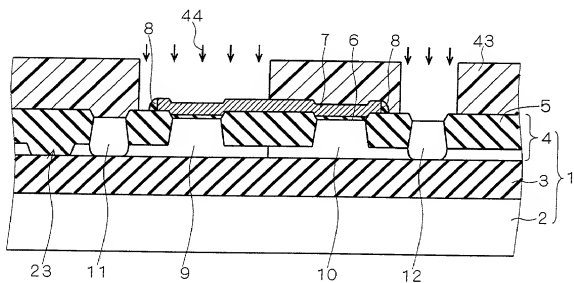


FIG. 16

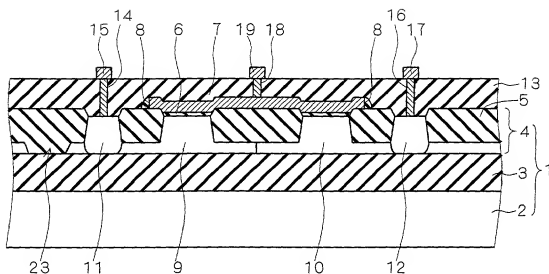


FIG. 17

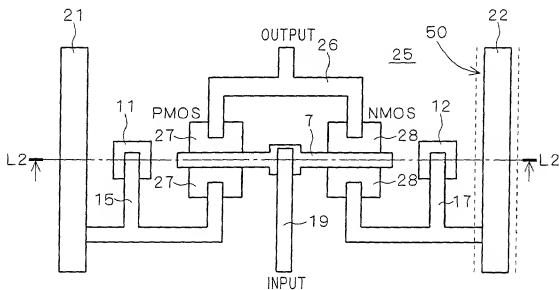


FIG. 18

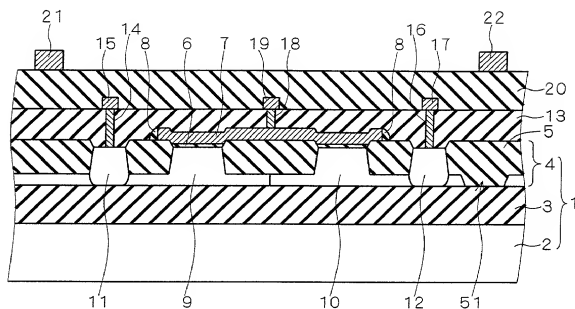
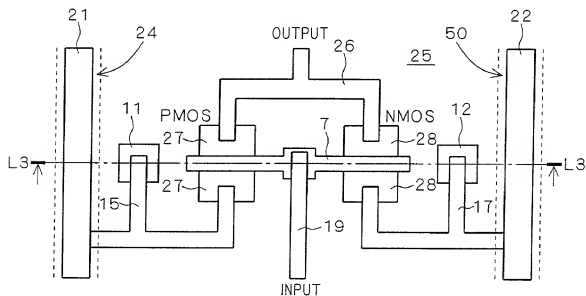


FIG. 19



This cross-sectional view shows a multi-layered assembly. At the bottom is a substrate (2). Above it is a base layer (3). A central layer (4) contains several rectangular openings (9, 10, 11, 12). This layer is flanked by side layers (5, 13). Above the central layer is another layer (6) with a central opening (7). This layer is flanked by side layers (8, 16). A top layer (20) contains several rectangular openings (14, 15, 17, 18). This layer is flanked by side layers (21, 22). A top layer (23) is at the very top. Various components are labeled with numbers: 2, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, 16, 17, 18, 19, 20, 21, 22, 23.

FIG. 22

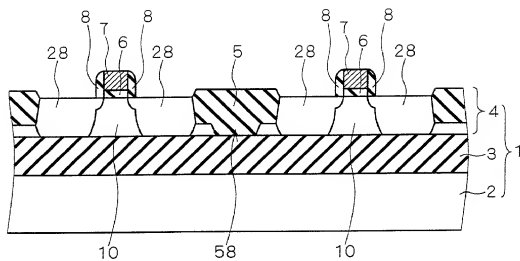


FIG. 23

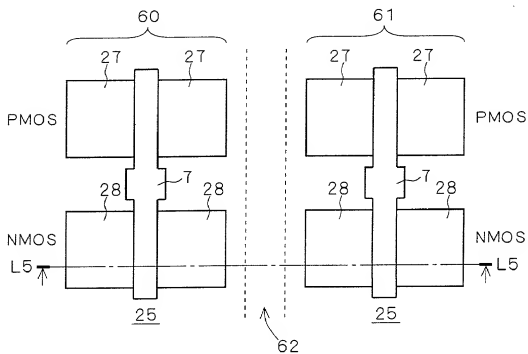


FIG. 24

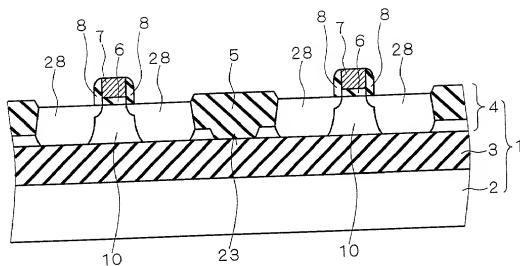
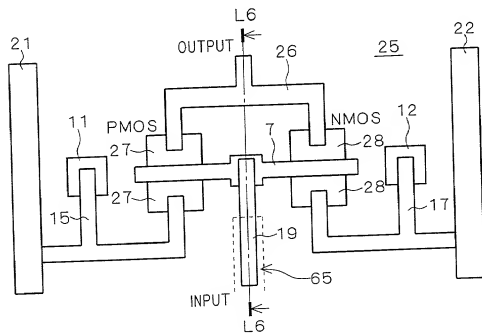


FIG. 25



F / G. 27 (A)

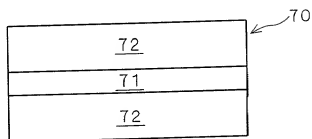


FIG. 27 (B)

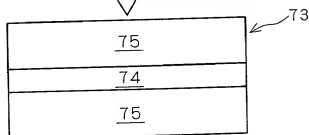


FIG. 28

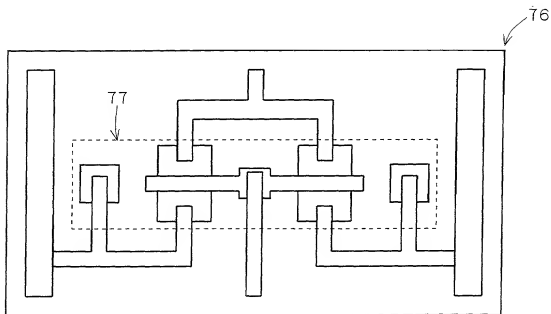


FIG. 29

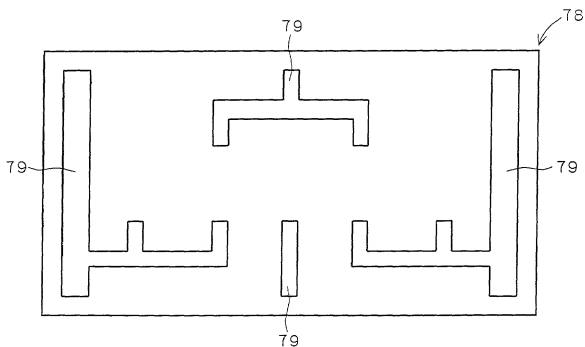
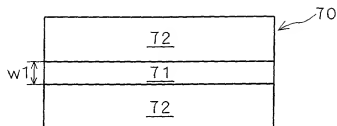
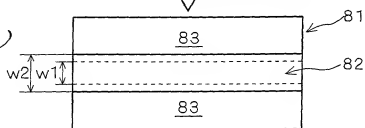


FIG. 30 (A)



↓ LOGIC INVERSION

FIG. 30 (B)



↓

FIG. 30 (C)

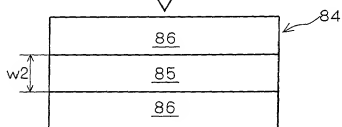


FIG. 31

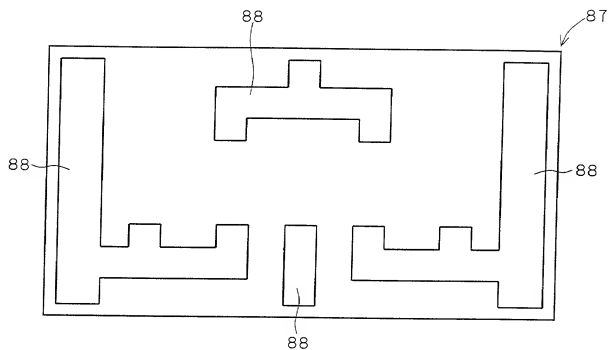


FIG. 32

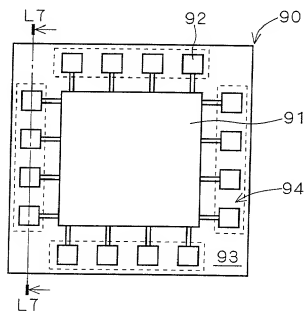


FIG. 33

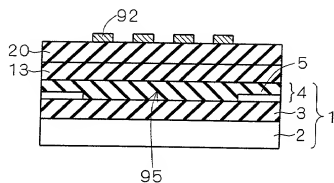


FIG. 34

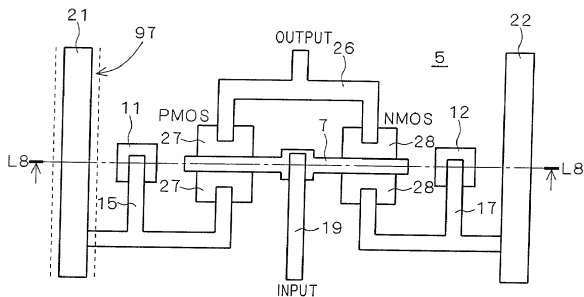


FIG. 35

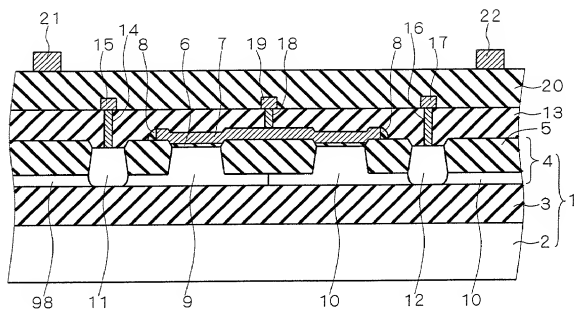


FIG. 36

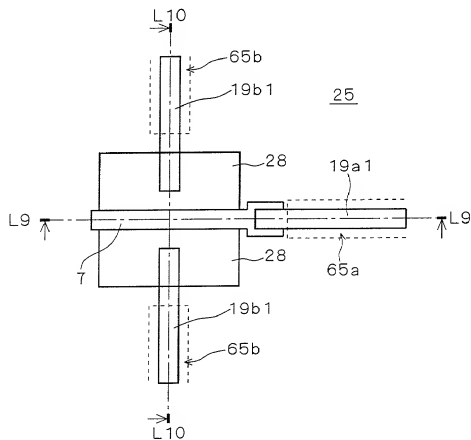


FIG. 37

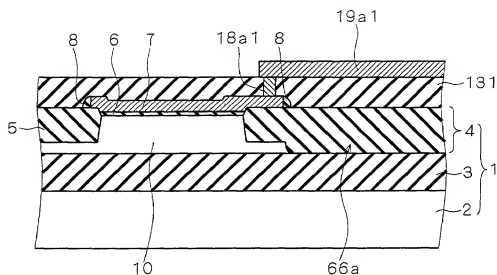
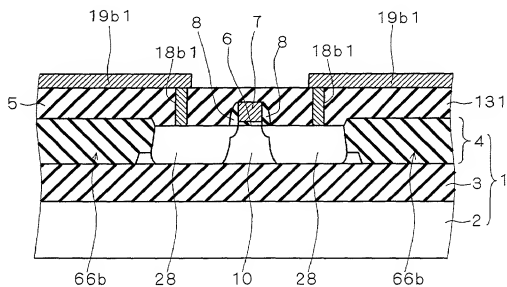


FIG. 38



CONCLUSIONS

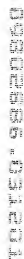
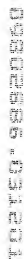
[illegible]

Figure 6



Figure 1



FIG. 43

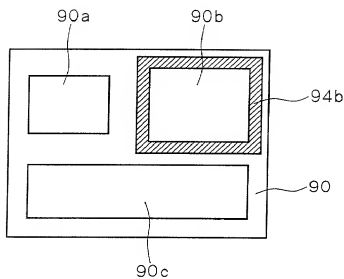


FIG. 44

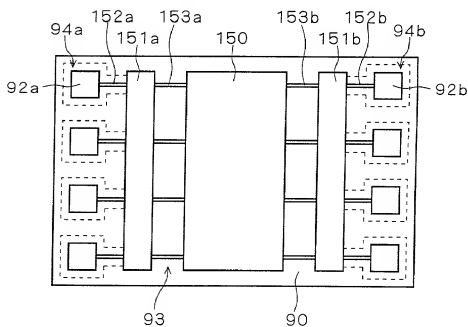


FIG. 45

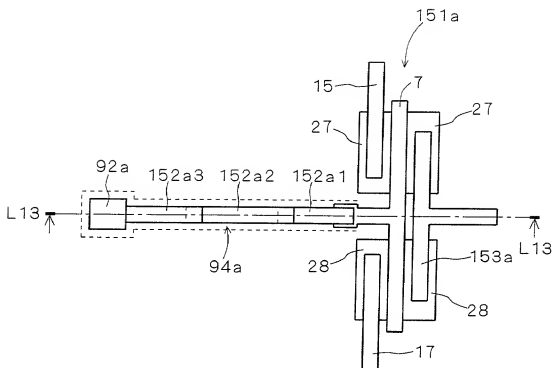
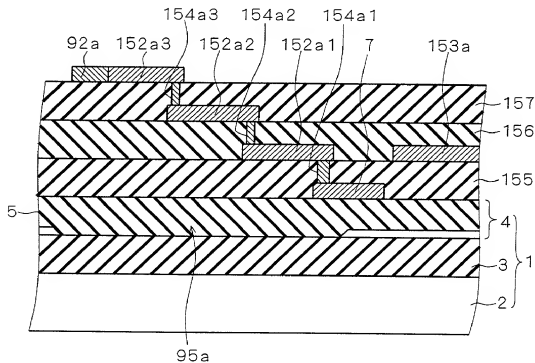
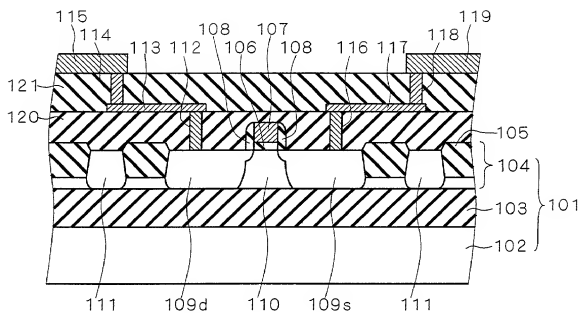


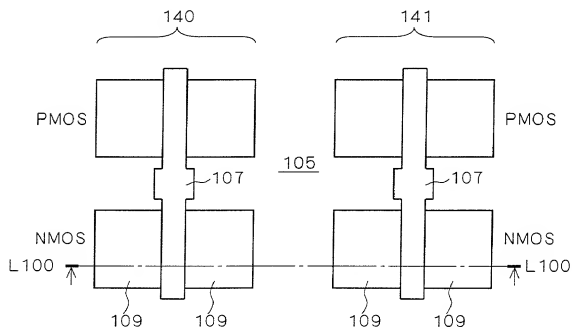
FIG. 46



F / G. 47



F / G. 48



F / G. 49

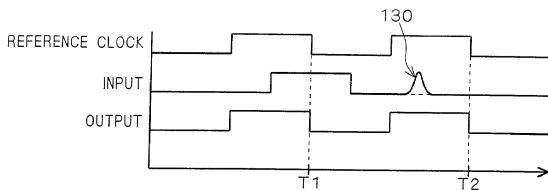
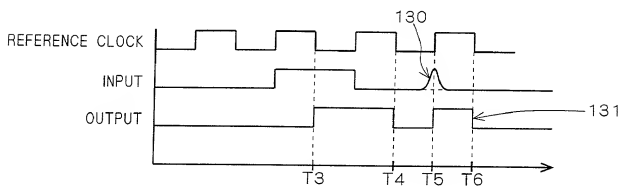


FIG. 50



F / G. 51

